









#### 30V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = 25°C
30V	20mΩ @ V <sub>GS</sub> = 10V	16.7A
	34mΩ @ V <sub>GS</sub> = 4.5V	12.6A

### **Description and Applications**

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- · Power management functions

### **Features and Benefits**

- · Low on-resistance
- Fast switching speed
- "Green" Component and RoHS compliant

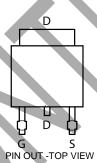
#### **Mechanical Data**

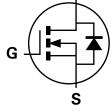
- Case: TO252-3L
- Case Material: Molded Plastic "Green" Molding Compound, UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (§3)
- Marking Information: See Below
- Ordering Information: See Below

Weight: 0.33 grams (approximate)



TOP VIEW





Equivalent Circuit

D

### Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3020LK3-13	N3020L	13	16	2,500

1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

## **Marking Information**

Notes:



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## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V <sub>DSS</sub>	30	V	
Gate-Source voltage			$V_{GS}$	±20	V	
		(Note 3)	<del>-</del>	16.7		
Continuous Drain current	$V_{GS} = 10V$	T <sub>A</sub> =70°C (Note 3)		13.3	Α	
		(Note 2)		11.3		
Pulsed Drain current	V <sub>GS</sub> = 10V	(Note 4)	I <sub>DM</sub>	51	A	
Continuous Source current (Body diode)		(Note 3)	I <sub>S</sub>	12	Α	
Pulsed Source current (Body diode) (Note 4)		I <sub>SM</sub>	51	A		

### Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
	(Note 2)		4.1 32.5		
Power dissipation Linear derating factor	(Note 3)	P <sub>D</sub>	8.9 71.4	W mW/°C	
	(Note 5)		2.17 17.4		
	(Note 2)		30.8		
Thermal Resistance, Junction to Ambient	(Note 3)	$R_{ heta JA}$	14.0	°C/W	
	(Note 5)		57.6		
Thermal Resistance, Junction to Lead	(Note 6)	$R_{ heta}$ JL	2.24	°C/W	
Operating and storage temperature range		$T_{J}, T_{STG}$	-55 to 150	°C	

Notes:

- 2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

- 3. Same as note 2, except the device is measured at t ≤ 10 sec.
  4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature.
  5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is
- measured when operating in a steady-state condition.

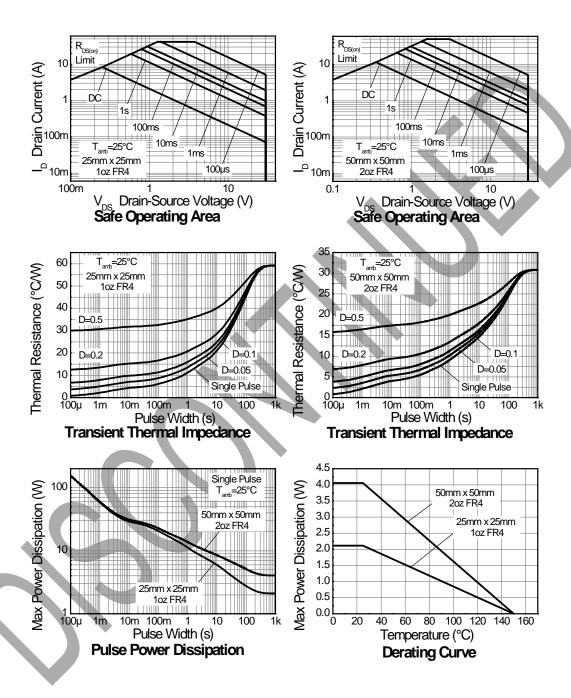
  6. Thermal resistance from junction to solder-point (at the end of the drain lead).







### Thermal Characteristics







## Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$I_D = 250 \mu A, V_{GS} = 0V$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	0.5	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	_	3.0	V .	$I_D$ = 250 $\mu$ A, $V_{DS}$ = $V_{GS}$
Static Drain-Source On-Resistance (Note 7)	Pro (our			0.020		V <sub>GS</sub> = 10V, I <sub>D</sub> = 7.0A
Static Dialif-Source Off-Nesistance (Note 1)	R <sub>DS</sub> (ON)			0.034		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.0A
Forward Transconductance (Notes 7 & 8)	<b>g</b> fs		16.5		S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 7.1A
Diode Forward Voltage (Note 7)	V <sub>SD</sub>		0.82	1.2	<b>&gt;</b>	I <sub>S</sub> = 1.7A, V <sub>GS</sub> = 0V
Reverse recovery time (Note 8)	t <sub>rr</sub>		12	_	ns	1 2 2 A di/dt 100 A/vo
Reverse recovery charge (Note 8)	Q <sub>rr</sub>	_	4.8	_	nC	I <sub>S</sub> = 2.2A, di/dt= 100A/μs
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C <sub>iss</sub>	_	608	1-1	pF	
Output Capacitance	Coss	_	132		pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V f= 1MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	71	-	pF	11 TIVII 12
Total Gate Charge	Qg		6.3	_	nC	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 4.5V I <sub>D</sub> = 7A
Total Gate Charge	$Q_g$		12.9		nC	
Gate-Source Charge	Q <sub>gs</sub>	_	2.5	_	nC	$V_{DS}$ = 15V, $V_{GS}$ = 10V
Gate-Drain Charge	Q <sub>gd</sub>	_	2.5	_	nC	I <sub>D</sub> = 7A
Turn-On Delay Time (Note 9)	t <sub>D(on)</sub>		2.9	_	ns	
Turn-On Rise Time (Note 9)	tr	-	3.3		ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V
Turn-Off Delay Time (Note 9)	t <sub>D(off)</sub>		16	_	ns	$I_D=$ 1A, $R_G\cong 6.0\Omega$
Turn-Off Fall Time (Note 9)	t <sub>f</sub>	_	8	_	ns	

Notes:

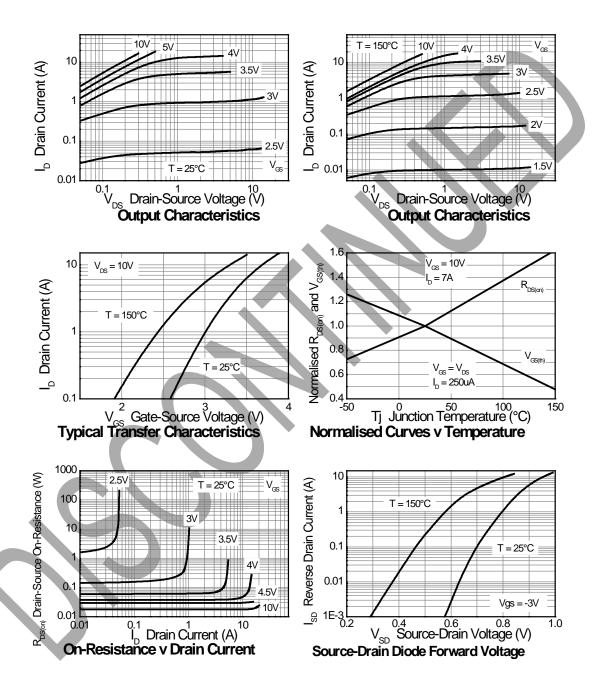
- Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
   For design aid only, not subject to production testing.
   Switching characteristics are independent of operating junction temperatures.





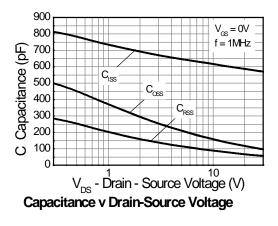


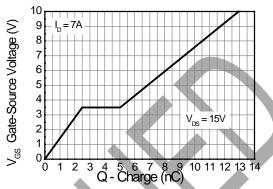
# **Typical Characteristics**





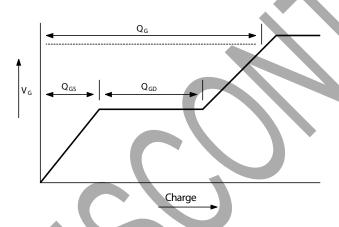
## **Typical Characteristics - continued**





Gate-Source Voltage v Gate Charge

### **Test Circuits**



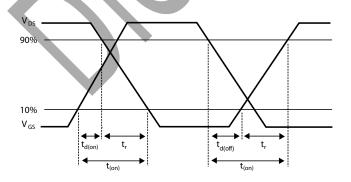
Current regulator

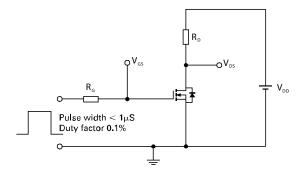
12V 0.2μ.F 50k D.U.T

V<sub>os</sub>

Basic gate charge waveform

Gate charge test circuit





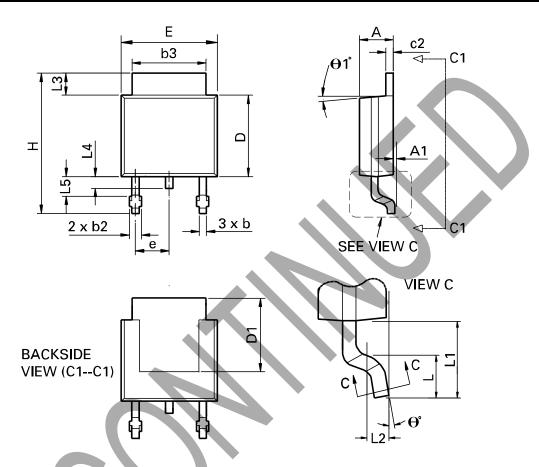
Switching time waveforms

Switching time test circuit





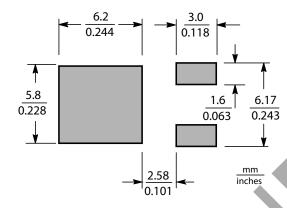
# **Package Outline Dimensions**



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A1		0.005	-	0.127	Н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
С	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	•1°	0°	10°	0°	10°
Е	0.250	0.265	6.35	6.73	• °	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-



### Suggested Pad Layout



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